DECL. **FION FOR PATENT APPLICATION (WITH POWER** ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled WAFER-LEVEL PACKAGE AND METHODS OF FABRICATING, the specification of which (check one):

| is attached hereto. | | | | |
|--|--|--|--|--|
| | States application serial no. | | | |
| was filed on as PCT in | ternational application no. | and was amended under PCT Article 19 or | 1 | |
| I hereby state that I have reviewed and ur referred to above. | derstand the contents of the above-io | dentified specification, including the claims, a | s amended by any amendment | |
| I acknowledge the duty to disclose to the | ILS Patent and Trademark Office al | l information known to me to be material to t | ha natantahilitu af sha auti | |
| matter claimed in this application, as "materia | ality" is defined in Title 37, Code of | Federal Regulations § 1.56. | ne patentability of the subject | |
| certificate or § 365(a) of any PCT internation attached continuation page and have also iden | al application(s) designating at least atified below and on any attached con | 119(a)-(d) or § 365(b) of any foreign applicat one country other than the United States of A ntinuation page any foreign application for pa e United States of America having a filing da | merica listed below and on any tent or inventor's certificate or | |
| Prior foreign/PCT application(s): | | | Priority Claimed | |
| (number) | (country) | (day/month/year filed | Yes No | |
| (number) | (country) | (day/month/year filed) | Yes No | |
| designating the United States of America liste application is not disclosed in any such prior the duty to disclose to the U.S. Patent and Treegulations § 1.56 which became available became | application in the manner provided be ademark Office all information know etween the filing date of such prior a | y the first paragraph of Title 35, United State on to me to be material to patentability as defi | es Code, § 112, I acknowledge ned in Title 37, Code of Federal | |
| (application serial no.) | (filing date) | (status - pending, patente | d or abandoned) | |
| (application serial no.) | (filing date) United States Code, § 119(e) of any | (status - pending, patente | , | |
| | | provinced approach (c) income | odow. | |
| (provisional application no.) | (filing date) | | | |
| I hereby appoint the following Registered I connected therewith: | Practitioners to prosecute this applica | tion and to transact all business in the Patent | and Trademark Office | |
| David V. Trask, Reg. No. 22,012 Laurence B. Bond, Reg. No. 30,549 Allen C. Turner, Reg. No. 33,041 Stephen R. Christian, Reg. No. 32,687 Kenneth C. Booth, Reg. No. 42,342 Lia M. Pappas, Reg. No. 34,095 | William S. Britt, Reg. No. 20,96 Joseph A. Walkowski, Reg. No. Kent S. Burningham, Reg. No. 3 Brick G. Power, Reg. No. 38,58 Samuel E. Webb, Reg. No. 44,3 | 28,765 James R. Duzan, Reg. No. 2 60,453 Edgar R. Cataxinos, Reg. N 11 Eleanor V. Goodall, Reg. N | Thomas J. Rossa, Reg. No. 26,799 James R. Duzan, Reg. No. 28,393 Edgar R. Cataxinos, Reg. No. 39,931 Eleanor V. Goodall, Reg. No. 35,162 Michael L. Lynch, Reg. No. 30,871 | |
| TRA P.O. | C. G. Power, telephone no. (801) 532 SK, BRITT & ROSSA BOX 2550 Lake City, Utah 84110 | -1922. | | |
| I hereby declare that all statements made he true; and further that these statements were may or both, under Section 1001 of Title 18 of the patent issued thereon. | ide with the knowledge that willful fa | and that all statements made on information a alse statements and the like so made are punis illful false statements may jeopardize the valid | shable by fine or imprisonment. | |
| Full name of first joint inventor: Salman Akra Inventor's signature | m Salver Akon | DateJune 15 th | 1999 | |

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DECLARATION FOR PATENT APPLICATION

(continuation page)

Date June 14, 1999

Invention title: WAFER-LEVEL PACKAGE AND METHODS OF FABRICATING

Inventor name(s) appearing on first declaration page: Salman Akram

Additional original, first and joint inventor(s):

Full name of second joint inventor: Alan G. Wood Inventor's signature

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